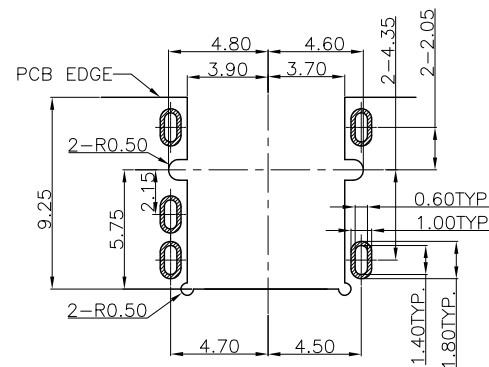
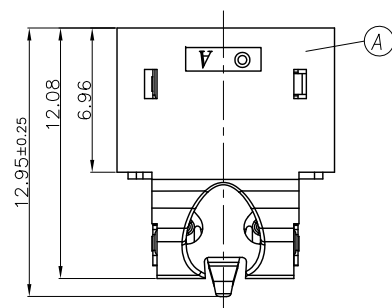


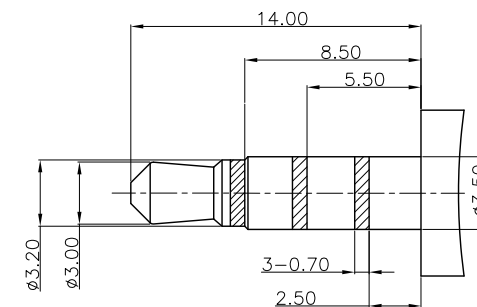
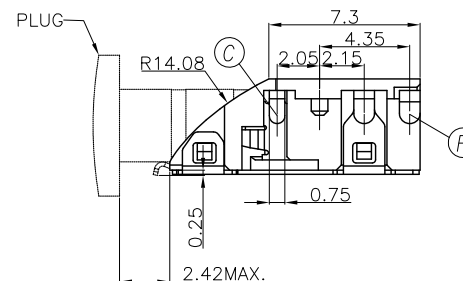
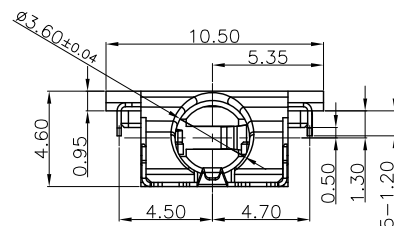
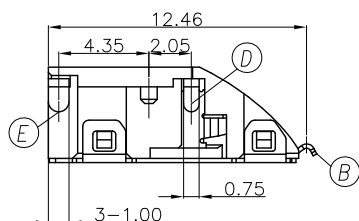
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO.:T121030-1A	HM-JIANG	2013.05.07



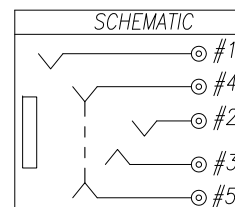
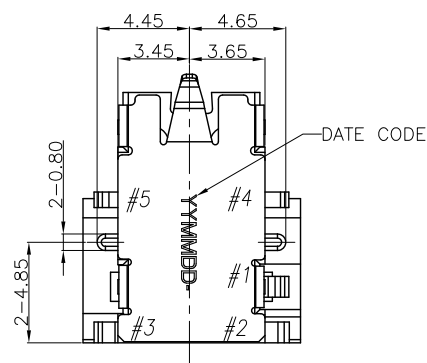
RECOMMENDED PCB LAYOUT(TOP VIEW),T=1.00
(TOLERANCE: ±0.05)

SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:
 - 1-1. RATING: 12V, 1A
 - 1-2. CONTACT RESISTANCE: 50mΩ MAX.(INITIAL)
 - 1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - 1-4. INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500V DC
- MECHANICAL CHARACTERISTICS:
 - 2-1. INSERTION FORCE : 0.3~3.0 KGF
 - 2-2. WITHDRAWAL FORCE : 0.3~3.0 KGF
- LIFE TEST: 5,000 CYCLES
- AFTER LIFE TEST, CONTACT RESISTANCE: 60mΩ MAX.
- AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT: ©
- HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:



3.5Ø 4POLE PLUG(TOLERANCE: ±0.05)



F	TIP SPRING	1	COPPER ALLOY, 0.25T	GOLD FLASH ON CONTACT AREA; ALL SOLDER NI 50u" MIN.PLATING.	
E	RING-A	1	COPPER ALLOY, 0.2T	GOLD FLASH ON CONTACT AREA; MATTE-TIN 120U" ON SOLDER TAIL AREA; ALL OVER NI 50u" PLATING.	
D	RING-B2	1	COPPER ALLOY, 0.2T	GOLD FLASH ON CONTACT AREA; GOLD FLASH ON SOLDER TAIL AREA; ALL OVER NI 50u" PLATING.	
C	RING-B1	1	COPPER ALLOY, 0.2T	GOLD FLASH ON CONTACT AREA; ALL OVER NI 50u" PLATING.	
B	EARTH	1	COPPER ALLOY, 0.2T	GOLD FLASH ON CONTACT AREA; ALL SOLDER NI 50u" MIN.PLATING.	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK	
NO	DESCRIPTION	QTY	MATERIAL		PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES		 Singatron Enterprise Co., Ltd. 信音企業股份有限公司			
DECIMALS: ANGLES:		TITLE	ø3.50 AUDIO JACK		
X :±0.5 X :±2°	DWN	HM-JIANG	PART NO. 2SJ3035-023111F		
X.X :±0.3 X.X :±1°	CHKD	BRUCE	SCALE:4:1	UNIT: mm	
X.XX :±0.2	APVD	LUSSEN	SIZE: A3	SHEET:1 OF 1	REV: A
CUSTOMER COPY					